GEL FLUX ED 1902



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No clean Gel Flux

(Item F42202)



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GEL FLUX ED 1902

GENERAL SPECIFICATIONS

Gel flux for repair / rework

Easy for repair / rework

Gel flux in syringe is useful to deposit a precise volume. It could be connected with an adaptator to a dispensing unit.

Designation	Item code
No clean gel flux, syringe of 10 cc with tappet	F42202

Flux Gel has been specially developed in relation to Solder Paste (Chemical and Alloys) for Surface Mount Technology (SMT) applications.

Use

- . Good contact with solder particles
- Avoids bridging of tracks
- . Compatibility with existing circuits
- . Very low residue

Economy

- . Requires approximately one fifth of material and application time
- . Costs less than Solder Paste

Environmental Benefi:

- . Improves contact with component leads
- . Waste does not contain lead

Gel flux has a base of high purity rosin with the equivalent activation of RMA (Rosin Mildly Active) to clean the metal oxides from the surface of the components and circuit boards in preparation for good solder fusion. The completed soldered connection will be the same as that produced with Solder Paste as had been applied by screen or stencil printing.

Gel flux is designed for "no-clean" technology. After soldering, the very low level of residue remaining may be left without risk of corrosion. It may also be removed however, if required, using a solvent cleaner.

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Physiochemical Characteristics:

Appearance: Gelatinous

Colour: Transparent Honey

Density: 1.01
Chlorine rate: < 0.05%
Non volatile
Viscosity: 400 Pas
Flash Point: 100°C

USE

Flux Gel due to its viscosity is an ideal flux for other applications:

As an alternative to Solder Paste where there is already sufficient solder alloy on the surface. For repair / rework where the component carries solder alloy on it's connecting surface

VARIOUS CHARACTERISTICS

Health and Safety:

Use in a well-ventilated area away from any source of ignition. Risk Classification R42/43 Safety Classification S3/7 and S24/25

Storage / Usable life:

Store in original containers at 6°C-10°C for approx. 12 months

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